



Final Product Change Notification

202212003F01 : Discontinuation of Gross Leak Screening of Radio Power Metal Ceramic Packaged Devices

Note: This notice is NXP Company Proprietary.

Issue Date: Dec 14, 2022 **Effective date:** Mar 14, 2023

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Management summary

This PCN communicates the discontinuation of 100% Gross Leak testing from the final manufacturing flow of all Radio Power air cavity devices. This discontinuation is the result of tightened environmental regulations that have caused the gross leak fluid supplier to discontinue supply. No viable alternative suppliers or materials are available. Process yields and reliability testing demonstrate that this process is no longer necessary for long term reliable operation in the field.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

PCN Overview

Description

Gross Leak screening of all Radio Power air cavity metal ceramic packaged devices will be discontinued.

Reason

Tightened environmental regulations/restrictions on the chemical compounds required for gross leak testing have resulted in discontinuation of the supply of these chemicals. As a result, NXP will no longer be able to perform gross leak screening.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from Dec 04, 2022

Production

Planned first shipment Mar 04, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

No Impact. Historically, screening yields have been very high and reliability testing of devices which do not pass the gross leak bubble test screening have passed all reliability tests without failure.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jan 13, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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